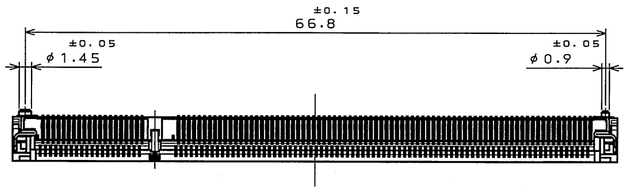
図面番号(DRAWING NO.) SJ100129

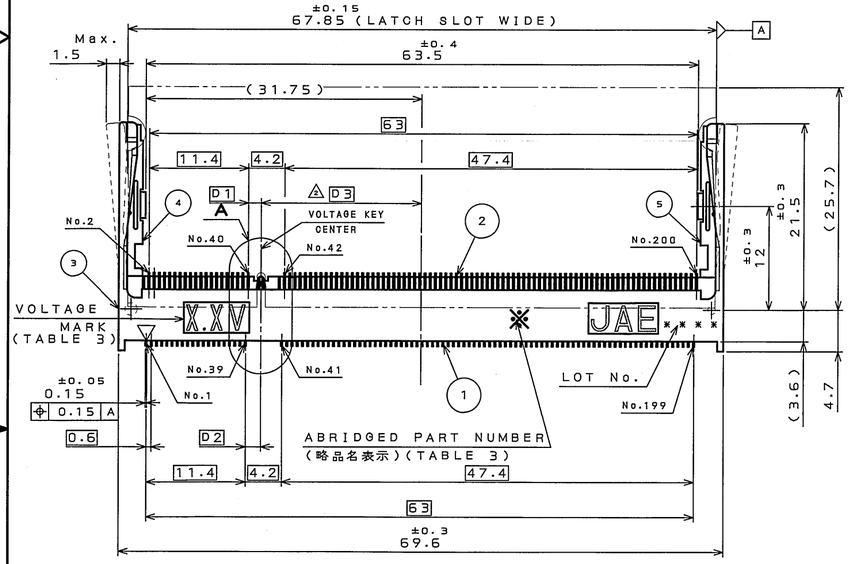
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITTING	E.MURANO	Y.YAHIRO	—	K.Hiratomi

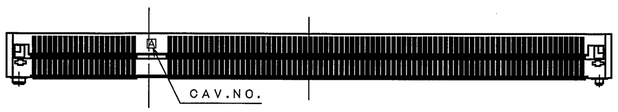
DESIGNATION

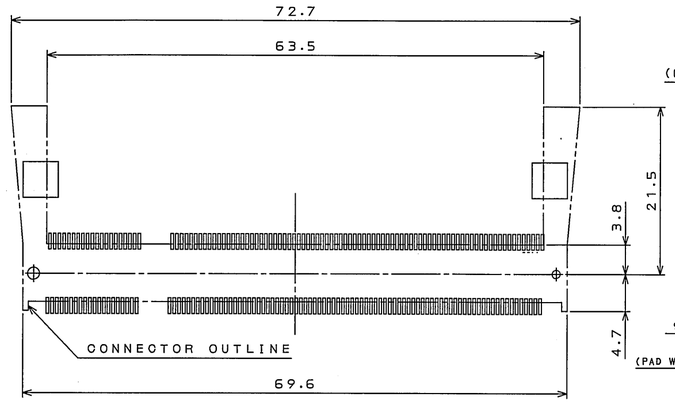
MM50−200B＊−＊E

- SERIES PREFIX シリーズ名
- NO. OF CONTACTS 芯数
- SOCKET TYPE ソケットタイプ B:LATCH TYPE SMT
- KEYING TYPE(DETAIL A) キィタイプ 2:TYPE B(1.8V) 1:TYPE A(2.5V)
- CONTACT FINISH 接点仕上げ 1:Au(0.1μm MIN) OVER NI 2:Au(0.3μm MIN) OVER NI
- 錫または錫合金(無鉛) (LEAD FREE)TIN/TIN ALLOY

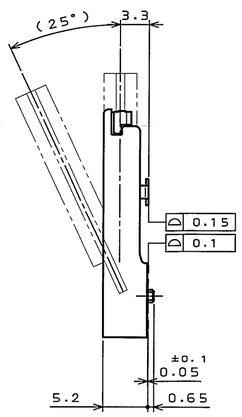


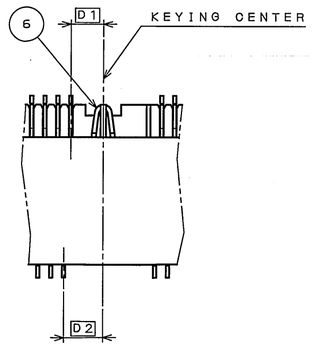






CONNECTOR MOUNTED AREA(REF.)





DETAIL A
(SCALE 5:1)
(REF.TABLE1)

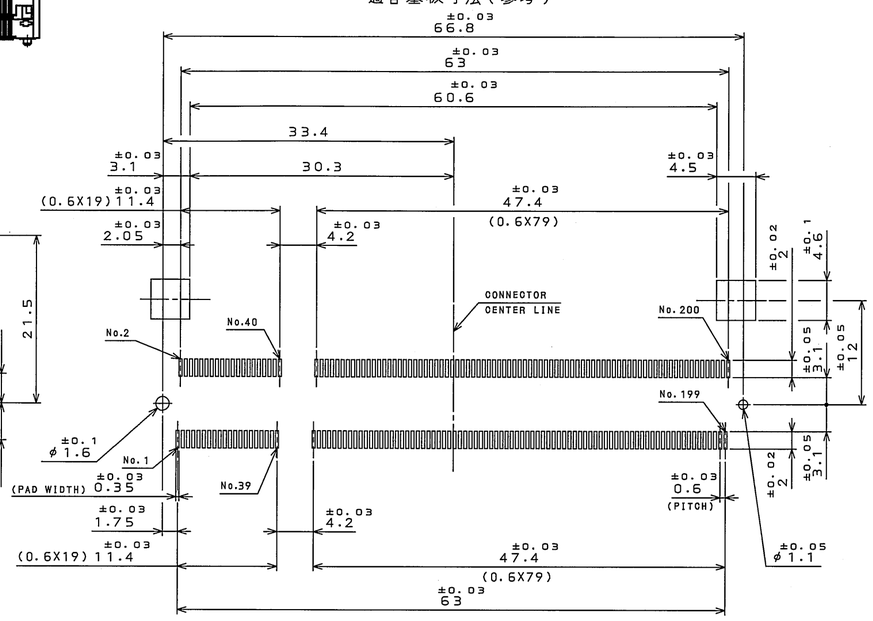
TABLE2
CONTACT FINISH

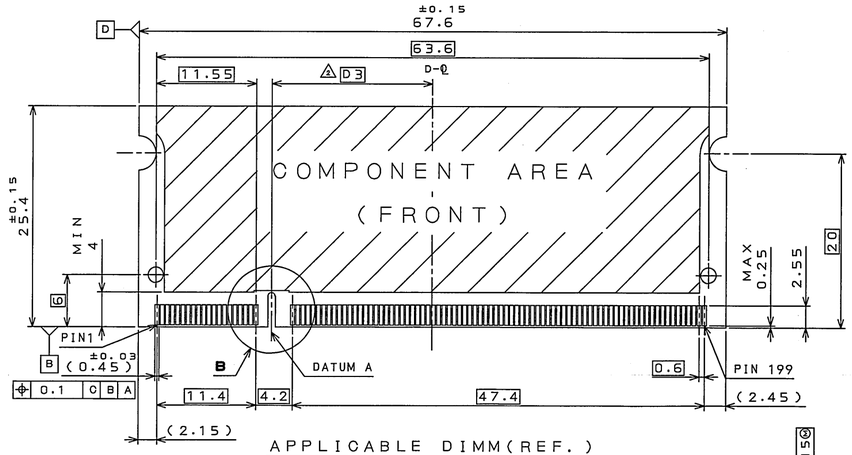
PARTS NAME	CONTACT AREA	SOLDERING AREA
MM50−200B＊−1E	Au(0.1μm Min.) OVER NI	GOLD FLASH OVER NI
MM50−200B＊−2E	Au(0.3μm Min.) OVER NI	GOLD FLASH OVER NI

TABLE3
DISCRIMINATION MARK

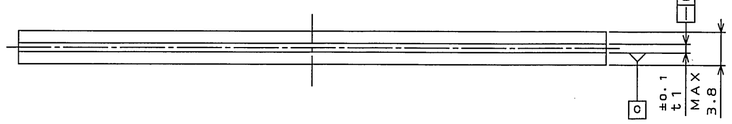
PARTS NAME	VOLTAGE MARK	ABRIDGED PART NUMBER
MM50−200B1−＊E	2.5V	＊E
MM50−200B2−＊E	1.8V	2−＊E

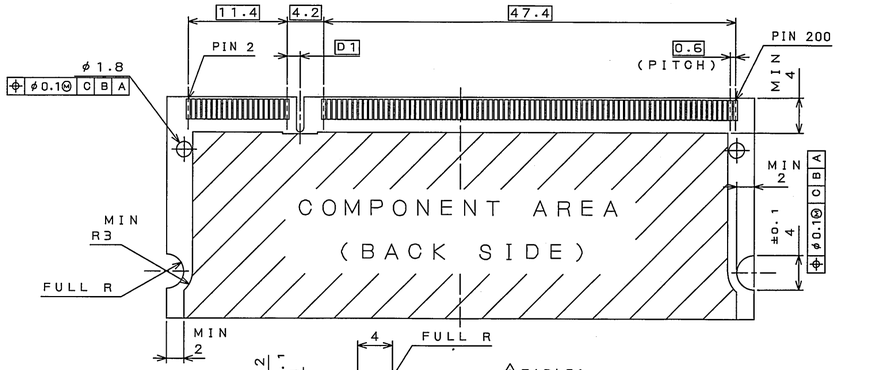
APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)





APPLICABLE DIMM(REF.)





DETAIL B

TABLE1
MECHANICAL KEYING

POWER SPPLY	D1	D2	D3
2.5V(TYPE A)	1.5	1.8	18.45
1.8V(TYPE B)	2.4	2.7	17.55

NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
6	KEY	1	STAINLESS	———	———
5	HOLD DOWN 2	1	PHOSPHOR BRONZE	TIN PLATING	———
4	HOLD DOWN 1	1	PHOSPHOR BRONZE	TIN PLATING	———
3	INSULATOR	1	GLASS FILLED LCP	———	UL94 V−0 COLOR WHITE
2	BOTTOM SIDE CONTACT	100	PHOSPHOR BRONZE	SEE TABLE 2	———
1	TOP SIDE CONTACT	100	PHOSPHOR BRONZE	SEE TABLE 2	———

仕様書(SPECIFICATION)	JACS−1655−01	第1版(ORIGINAL DATE)	24.Oct.2003
一般公差(GENERAL TOLERANCE)		製図 DR.	
寸法(DIMENSION)	角度(ANGLES)	担当 CHK.	R.KATOU
. ±0.8	×° ±	査閲 APPD.	Y.YAHIRO
.× ±0.4	×°×' ±	承認 APPD.	S.KASHIWAGI
.×× ±0.1			
.××× ±			

尺度(SCALE)	2:1
シリーズ(SERIES)	MM50
名称(TITLE)	MM50 −200B＊−＊E
質量(MASS)	
日本航空電子工業株式会社	JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
図面番号(DRAWING NO.)	SJ100129
版数(REV.)	2
SIZE	A2

LEAD FREE この製品は鉛フリー品です

JAE-CONNECTOR.COM Reference Only

JAE CONNECTOR DIV. PROPRIETARY.
COPYRIGHT (C) 2003, JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

DOF-0-213F(05.08)

0 10 20 30 40 50 60 70 80 90 100